

SILICON CONDENSER MICROPHONE**ABSTRACT OF THE DISCLOSURE**

Provided is a silicon condenser microphone using a case
5 in which a plating layer is formed on a body formed of resin.
The silicon condenser microphone includes: a case having a
can-shaped body with one side open, the body being formed of
a resin, and a plating layer formed on the body; and a
substrate on which a micro electro mechanical system (MEMS)
10 microphone chip and an application-specific integrated
circuit (ASIC) chip for processing an electrical signal are
mounted, a connection pattern for attaching the case is
formed, and the case is attached to the connection pattern
using a conductive adhesive. The case may be formed in a
15 cylindrical shape or a rectangular box shape. The plating
layer may be formed on an inner surface, an outer surface, or
an entire surface of the body and a step may be formed along
an inner periphery on an end portion of an opening surface of
the body. The body is formed of easily moldable resin and
20 the plating layer is formed on the inner, outer, or entire
surface of the body to prevent an external noise such as an
electromagnetic wave noise from being received from the
outside.

25 Figure 3